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electronic device thereon, pins of the electronic device extending through holes defined in the cover and partially extending into the contact receiving bores [holes] whereby when the cover is moved with respect to the base, the pins are brought into contact with and thus electrically engage with the contacts. <sup>B2</sup> the base plate additionally defining a plurality of holes not having contacts therein, <sup>B</sup> said holes being arranged in a particular pattern on the base plate, [wherein] the base plate [is] further being made of a dielectric material, said dielectric material being completely and uniformly distributed in the base plate and having a regular arrangement of molecules, said regular arrangement of molecules being achieved by means of injection molding the base plate with a mold comprising core pins whereby the base plate molded thereby defines [a] the plurality of holes in [a predetermined] the particular pattern, said pattern having been determined empirically to reduce, both by arrangement of said plurality of holes in the finished base plate and by promotion of said regular arrangement of molecules during the injection molding process, [for reducing] a difference between thermal expansion coefficients of the base plate in first and second directions substantially normal to each other. <sup>B3</sup>

Claim <sup>2</sup>13. (amended) The electrical connector as claimed in Claim <sup>1</sup>12, wherein the holes in the base plate are rhombic with a major diagonal direction thereof being substantially parallel to a flowing direction of a plasticized fluid of the dielectric material during injection molding.

Claim <sup>3</sup>14. (amended) The electrical connector as claimed in Claim <sup>1</sup>12, wherein at least some of the holes formed in adjacent rows in the base plate are alternately arranged [in rows].

In Claim 15, line 2, please change "crystal" to crystalline..

In Claim 16, lines 3 and 4, please insert -substantially close to— before 13 x 10<sup>-6</sup> in line 3 and before 22 x 10<sup>-6</sup> in line 4.

Please amend Claims 19 and 20 as follows:

Claim <sup>8</sup>19 (amended) The electrical connector as claimed in Claim 12, wherein the holes defined in the base plate are elliptical in shape with a direction of a major axis [with a major direction] thereof being substantially parallel to a flowing direction of a plasticized fluid of the dielectric material during injection molding.

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Claim 20 (amended) An electrical assembly comprising a connector and a circuit board, said connector including at least a base plate retaining a plurality of conductive contacts thereto, each of said contacts being attached to the circuit board via a solder ball positioned at a tip of a tail portion of the contact, which is exposed to a bottom of the base plate, said base plate defining a plurality of holes around the contacts wherein a size, shape, and arrangement pattern of said holes has been empirically determined to modify [are designedly arranged to be properly located, dimensioned and shaped so that] a thermal expansion coefficient of said base plate both along a lateral dimension and along a longitudinal dimension of said base plate so that said thermal expansion coefficients are [is modified to be] substantially close to that of the circuit board for preventing breakage of said solder balls.

Please add new Claim 21 as follows.

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21. A dielectric plate produced by the following method:
- (a) providing a mold for injection-molding the dielectric plate;
  - (b) determining locations, sizes and shapes of core pins of the mold;
  - (c) injecting a plasticized dielectric material into the mold to form the dielectric plate wherein the core

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pins guide a flow of the plasticized dielectric material whereby molecules of the dielectric material are regularly oriented; and  
(d) curing and forming the dielectric plate in which holes corresponding to the core pins are formed.

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